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Details

E·XFI

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	12
Program Memory Size	768B (512 x 12)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	25 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c54at-20-so

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



FIGURE 3-1: PIC16C5X SERIES BLOCK DIAGRAM

TABLE 5-3: RESET CONDITIONS FOR ALL REGISTERS

Register	Address	Power-On Reset	MCLR or WDT Reset
W	N/A	xxxx xxxx	uuuu uuuu
TRIS	N/A	1111 1111	1111 1111
OPTION	N/A	11 1111	11 1111
INDF	00h	xxxx xxxx	uuuu uuuu
TMR0	01h	XXXX XXXX	uuuu uuuu
PCL	02h	1111 1111	1111 1111
STATUS	03h	0001 1xxx	000q quuu
FSR ⁽¹⁾	04h	1xxx xxxx	luuu uuuu
PORTA	05h	xxxx	uuuu
PORTB	06h	XXXX XXXX	uuuu uuuu
PORTC ⁽²⁾	07h	XXXX XXXX	uuuu uuuu
General Purpose Register Files	07-7Fh	xxxx xxxx	սսսս սսսս

Legend: x = unknown u = unchanged - = unimplemented, read as '0'<math>q = see tables in Table 5-1 for possible values.

- Note 1: These values are valid for PIC16C57/CR57/CR58/CR58. For the PIC16C54/CR54/C55/C56/CR56, the value on RESET is 111x xxxx and for MCLR and WDT Reset, the value is 111u uuuu.
 - **2:** General purpose register file on PIC16C54/CR54/C56/CR56/C58/CR58.

FIGURE 5-1: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



6.0 MEMORY ORGANIZATION

PIC16C5X memory is organized into program memory and data memory. For devices with more than 512 bytes of program memory, a paging scheme is used. Program memory pages are accessed using one or two STATUS Register bits. For devices with a data memory register file of more than 32 registers, a banking scheme is used. Data memory banks are accessed using the File Selection Register (FSR).

6.1 Program Memory Organization

The PIC16C54, PIC16CR54 and PIC16C55 have a 9bit Program Counter (PC) capable of addressing a 512 x 12 program memory space (Figure 6-1). The PIC16C56 and PIC16CR56 have a 10-bit Program Counter (PC) capable of addressing a 1K x 12 program memory space (Figure 6-2). The PIC16CR57, PIC16C58 and PIC16CR58 have an 11-bit Program Counter capable of addressing a 2K x 12 program memory space (Figure 6-3). Accessing a location above the physically implemented address will cause a wraparound.

A NOP at the RESET vector location will cause a restart at location 000h. The RESET vector for the PIC16C54, PIC16CR54 and PIC16C55 is at 1FFh. The RESET vector for the PIC16C56 and PIC16CR56 is at 3FFh. The RESET vector for the PIC16C57, PIC16CR57, PIC16C58, and PIC16CR58 is at 7FFh. See Section 6.5 for additional information using CALL and GOTO instructions.

FIGURE 6-1: PIC16C54/CR54/C55 PROGRAM MEMORY MAP AND STACK



FIGURE 6-2:

PIC16C56/CR56 PROGRAM MEMORY MAP AND STACK



FIGURE 6-3:

PIC16C57/CR57/C58/ CR58 PROGRAM MEMORY MAP AND STACK









6.4 **OPTION Register**

The OPTION Register is a 6-bit wide, write-only register which contains various control bits to configure the Timer0/WDT prescaler and Timer0.

By executing the OPTION instruction, the contents of the W Register will be transferred to the OPTION Register. A RESET sets the OPTION<5:0> bits.

REGISTER 6-2: OPTION REGISTER

U-0	U-0	W-1	W-1	W-1	W-1	W-1	W-1
_	—	T0CS	TOSE	PSA	PS2	PS1	PS0
bit 7							bit 0

- bit 7-6: Unimplemented: Read as '0'
- bit 5: **TOCS**: Timer0 clock source select bit
 - 1 = Transition on T0CKI pin
 - 0 = Internal instruction cycle clock (CLKOUT)
- bit 4: **TOSE**: Timer0 source edge select bit
 - 1 = Increment on high-to-low transition on T0CKI pin
 - 0 = Increment on low-to-high transition on T0CKI pin
- bit 3: **PSA**: Prescaler assignment bit
 - 1 = Prescaler assigned to the WDT
 - 0 = Prescaler assigned to Timer0

bit 2-0: **PS<2:0>:** Prescaler rate select bits

Bit Value	Timer0 Rate	WDT Rate
000	1:2	1:1
001	1:4	1:2
010	1:8	1:4
011	1:16	1:8
100	1:32	1:16
101	1:64	1:32
110	1 : 128	1:64
111	1 : 256	1 : 128

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, re	ead as '0'
-n = Value at POR	1 = bit is set	0 = bit is cleared	x = bit is unknown

6.5.1 PAGING CONSIDERATIONS – PIC16C56/CR56, PIC16C57/CR57 AND PIC16C58/CR58

If the Program Counter is pointing to the last address of a selected memory page, when it increments it will cause the program to continue in the next higher page. However, the page preselect bits in the STATUS Register will not be updated. Therefore, the next GOTO, CALL or modify PCL instruction will send the program to the page specified by the page preselect bits (PA0 or PA<1:0>).

For example, a NOP at location 1FFh (page 0) increments the PC to 200h (page 1). A GOTO xxx at 200h will return the program to address xxh on page 0 (assuming that PA<1:0> are clear).

To prevent this, the page preselect bits must be updated under program control.

6.5.2 EFFECTS OF RESET

The Program Counter is set upon a RESET, which means that the PC addresses the last location in the last page (i.e., the RESET vector).

The STATUS Register page preselect bits are cleared upon a RESET, which means that page 0 is pre-selected.

Therefore, upon a RESET, a GOTO instruction at the RESET vector location will automatically cause the program to jump to page 0.

6.6 Stack

PIC16C5X devices have a 10-bit or 11-bit wide, two-level hardware push/pop stack.

A CALL instruction will push the current value of stack 1 into stack 2 and then push the current program counter value, incremented by one, into stack level 1. If more than two sequential CALL's are executed, only the most recent two return addresses are stored.

A RETLW instruction will pop the contents of stack level 1 into the program counter and then copy stack level 2 contents into level 1. If more than two sequential RETLW's are executed, the stack will be filled with the address previously stored in level 2. Note that the W Register will be loaded with the literal value specified in the instruction. This is particularly useful for the implementation of data look-up tables within the program memory.

For the RETLW instruction, the PC is loaded with the Top of Stack (TOS) contents. All of the devices covered in this data sheet have a two-level stack. The stack has the same bit width as the device PC, therefore, paging is not an issue when returning from a subroutine.

AC Chara	octeristics	$ \begin{array}{ll} \mbox{Standard Operating Conditions (unless otherwise specified)} \\ \mbox{Operating Temperature} & 0^{\circ}C \leq TA \leq +70^{\circ}C \ \ for \ commercial \\ -40^{\circ}C \leq TA \leq +85^{\circ}C \ \ for \ industrial \\ -40^{\circ}C \leq TA \leq +125^{\circ}C \ \ for \ extended \\ \end{array} $					
Param No.	Symbol	Characteristic	Min	Тур†	Max	Units	Conditions
1	Tosc	External CLKIN Period ⁽¹⁾	250		—	ns	XT OSC mode
			250	—		ns	HS OSC mode (04)
			100	—		ns	HS osc mode (10)
			50	—	—	ns	HS osc mode (20)
			5.0	_	—	μs	LP OSC mode
		Oscillator Period ⁽¹⁾	250	—		ns	RC OSC mode
			250	—	10,000	ns	XT OSC mode
			250	—	250	ns	HS OSC mode (04)
			100	—	250	ns	HS osc mode (10)
			50	—	250	ns	HS OSC mode (20)
			5.0		200	μS	LP OSC mode
2	Тсу	Instruction Cycle Time ⁽²⁾	—	4/Fosc	—	—	
3	TosL, TosH	Clock in (OSC1) Low or High	50*	—	—	ns	XT oscillator
		lime	20*	—	—	ns	HS oscillator
			2.0*		—	μS	LP oscillator
4	TosR, TosF	Clock in (OSC1) Rise or Fall	—	—	25*	ns	XT oscillator
		Time	—	—	25*	ns	HS oscillator
			—	—	50*	ns	LP oscillator

TABLE 13-1:	EXTERNAL CLOCK TIMING REQUIREMENT	S - PIC16CR54A

These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

when an external clock input is used, the "max" cycle time limit is "Du" (no clock) for all device

2: Instruction cycle period (TcY) equals four times the input oscillator time base period.

TABLE 14-2: INPUT CAPACITANCE FOR PIC16C54/56

Pin	Typical Capacitance (pF)			
FIII	18L PDIP	18L SOIC		
RA port	5.0	4.3		
RB port	5.0	4.3		
MCLR	17.0	17.0		
OSC1	4.0	3.5		
OSC2/CLKOUT	4.3	3.5		
TOCKI	3.2	2.8		

All capacitance values are typical at 25° C. A part-to-part variation of ±25% (three standard deviations) should be taken into account.

TABLE 14-3:	INPUT CAPACITANCE FOR
	PIC16C55/57

	Typical Capacitance (pF)				
Pin	28L PDIP (600 mil)	28L SOIC			
RA port	5.2	4.8			
RB port	5.6	4.7			
RC port	5.0	4.1			
MCLR	17.0	17.0			
OSC1	6.6	3.5			
OSC2/CLKOUT	4.6	3.5			
TOCKI	4.5	3.5			

All capacitance values are typical at 25° C. A part-to-part variation of ±25% (three standard deviations) should be taken into account.

$\begin{tabular}{lllllllllllllllllllllllllllllllllll$					i fied) rcial al al - PIC16LV54A-02I ed		
Param No.	Symbol	Characteristic Min Typ† Max Units Conditions					
1	Tosc	External CLKIN Period ⁽¹⁾	250			ns	XT OSC mode
			500	—	—	ns	XT osc mode (PIC16LV54A)
			250	—	—	ns	HS osc mode (04)
			100	—	—	ns	HS osc mode (10)
			50	—	—	ns	HS osc mode (20)
			5.0	_	—	μS	LP OSC mode
		Oscillator Period ⁽¹⁾	250	—	_	ns	RC osc mode
			500	—	—	ns	RC osc mode (PIC16LV54A)
			250	—	10,000	ns	XT OSC mode
			500	—	—	ns	XT osc mode (PIC16LV54A)
			250	—	250	ns	HS osc mode (04)
			100	—	250	ns	HS osc mode (10)
			50	—	250	ns	HS osc mode (20)
			5.0	—	200	μS	LP OSC mode
2	Тсу	Instruction Cycle Time ⁽²⁾		4/Fosc	_		
3	TosL, TosH	Clock in (OSC1) Low or	85*	—	—	ns	XT oscillator
		High Lime	20*	—	—	ns	HS oscillator
			2.0*	—	—	μS	LP oscillator
4	TosR, TosF	Clock in (OSC1) Rise or	—	—	25*	ns	XT oscillator
		Fall lime	—	_	25*	ns	HS oscillator
			_	_	50*	ns	LP oscillator

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

2: Instruction cycle period (TcY) equals four times the input oscillator time base period.

16.0 DEVICE CHARACTERIZATION - PIC16C54A

The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

"Typical" represents the mean of the distribution at 25°C. "Maximum" or "minimum" represents (mean + 3σ) or (mean - 3σ) respectively, where σ is a standard deviation, over the whole temperature range.



FIGURE 16-1: TYPICAL RC OSCILLATOR FREQUENCY vs. TEMPERATURE

TABLE 16-1: RC OSCILLATOR FREQUENCIES

Сехт	Rext	Average Fosc @ 5 V, 25°C				
20 pF	3.3K	5 MHz	± 27%			
	5K	3.8 MHz	± 21%			
	10K	2.2 MHz	± 21%			
	100K	262 kHz	± 31%			
100 pF	3.3K	1.6 MHz	± 13%			
	5K	1.2 MHz	± 13%			
	10K	684 kHz	± 18%			
	100K	71 kHz	± 25%			
300 pF	3.3K	660 kHz	± 10%			
	5.0K	484 kHz	± 14%			
	10K	267 kHz	± 15%			
	100K	29 kHz	± 19%			

The frequencies are measured on DIP packages.

The percentage variation indicated here is part-to-part variation due to normal process distribution. The variation indicated is ± 3 standard deviation from average value for VDD = 5V.

FIGURE 16-4: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD, CEXT = 300 PF, 25°C

PIC16C5X

FIGURE 16-5: TYPICAL IPD vs. VDD, WATCHDOG DISABLED (25°C)

FIGURE 16-12: TYPICAL IDD vs. FREQUENCY (WDT DISABLED, RC MODE @ 100 PF, 25°C)

FIGURE 16-13: MAXIMUM IDD vs. FREQUENCY (WDT DISABLED, RC MODE @ 100 PF, -40°C to +85°C)

17.1 DC Characteristics:PIC16C54C/C55A/C56A/C57C/C58B-04, 20 (Commercial, Industrial) PIC16LC54C/LC55A/LC56A/LC57C/LC58B-04 (Commercial, Industrial) PIC16CR54C/CR56A/CR57C/CR58B-04, 20 (Commercial, Industrial) PIC16LCR54C/LCR56A/LCR57C/LCR58B-04 (Commercial, Industrial)

PIC16LC5X PIC16LCR5X (Commercial, Industrial)			$ \begin{array}{ll} \mbox{Standard Operating Conditions (unless otherwise specified)} \\ \mbox{Operating Temperature} & 0^{\circ}C \leq TA \leq +70^{\circ}C \mbox{ for commercial} \\ -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ for industrial} \end{array} $					
PIC16C5X PIC16CR5X (Commercial, Industrial)			$ \begin{array}{ll} \mbox{Standard Operating Conditions (unless otherwise specified)} \\ \mbox{Operating Temperature} & 0^{\circ}\mbox{C} \leq T\mbox{A} \leq +70^{\circ}\mbox{C} \mbox{ for commercial} \\ -40^{\circ}\mbox{C} \leq T\mbox{A} \leq +85^{\circ}\mbox{C} \mbox{ for industrial} \\ \end{array} $					
Symbol	Characteristic/Device	Min	Тур†	Max	Units	Conditions		
IDD	Supply Current ^(2,3)							
	PIC16LC5X		0.5	2.4	mA	Fosc = 4.0 MHz, VDD = 5.5V, XT and		
			11	27	μA	RC modes		
						FOSC = 32 kHz , VDD = 2.5V, LP mode,		
			14	35	μA	Commercial Ease $= 22 \text{ kHz}$ Vpp $= 2.5 \text{ // LP mode}$		
						Industrial		
	PIC16C5X	_	1.8	2.4	mA	Fosc = 4 MHz, VDD = 5.5V, XT and RC		
			2.6	3.6*	mA	modes		
		—	4.5	16	mA	FOSC = 10 MHz, VDD = 3.0V, HS mode		
			14	32	μA	FOSC = 20 MHz, VDD = 5.5 V, HS mode		
			47	40		POSC = 32 kHz, VDD = 3.0 V, LP mode,		
		_	17	40	μA	Commercial		
						Industrial		
	5X R5X ercial, Indu Symbol	5X R5X ercial, Industrial) X 5X ercial, Industrial) Symbol Characteristic/Device IDD Supply Current ^(2,3) PIC16LC5X PIC16C5X	SX Stand: Opera R5X Opera ercial, Industrial) Stand: Opera Symbol Characteristic/Device Min IDD Supply Current ^(2,3) — PIC16LC5X — — — — — — — — — — — — — — — — — — — — — — — — — — — — — — — — — — — — — —	SX R5X ercial, Industrial) Standard Ope Operating Tem Operating Tem Operating Tem Symbol Characteristic/Device Min Typ† IDD Supply Current ^(2,3) Min Typ† IDD Supply Current ^(2,3) 0.5 IDD PIC16LC5X — 0.5 IDD PIC16LC5X — 14 IDD 14 14 IDD 14 14	SX R5X ercial, Industrial) Standard Operating Operating Temperatu Operating Temperatu Symbol Characteristic/Device Min Typ† Max IDD Supply Current ^(2,3) 91C16LC5X 0.5 2.4 11 27 14 35 PIC16C5X 1.8 2.4 14 35 14 32 14 32 14 32 14 32 17 40	5X Standard Operating Condit Operating Temperature 6x Standard Operating Condit Operating Temperature 6x Standard Operating Condit Operating Temperature 5x Standard Operating Condit Operating Temperature 5x Standard Operating Condit Operating Temperature Symbol Characteristic/Device Min Typ† Max Units IDD Supply Current ^(2,3) PIC16LC5X — 0.5 2.4 mA IDD PIC16LC5X — 11 27 µA IDD PIC16C5X — 1.8 2.4 mA IDD PIC16C5X — 1.8 2.4 mA IDD IDD PIC16C5X — 1.8 2.4 mA IDD IDD <t< td=""></t<>		

Legend: Rows with standard voltage device data only are shaded for improved readability.

* These parameters are characterized but not tested.

- † Data in "Typ" column is at 5V, 25°C, unless otherwise stated. These parameters are for design guidance only, and are not tested.
- Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.
 - 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.
 - a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, MCLR = VDD; WDT enabled/disabled as specified.
 - b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.
 - 3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in k Ω .

PIC16C5X

FIGURE 18-10: VTH (INPUT THRESHOLD TRIP POINT VOLTAGE) OF OSC1 INPUT (IN XT, HS AND LP MODES) vs. VDD

FIGURE 18-17: PORTA, B AND C IOL vs. Vol, VDD = 3 V

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IABLE 19-2:	CLKOUT AND I/O TIMING REQUIREMENTS - PIC16C5X-40

AC Chara	AC CharacteristicsStandard Operating Conditions (unless otherwise specified) Operating Temperature $0^{\circ}C \le TA \le +70^{\circ}C$ for commercial					
Param No.	Symbol	Characteristic	Min	Тур†	Max	Units
10	TosH2ckL	OSC1↑ to CLKOUT↓ ^(1,2)		15	30**	ns
11	TosH2ckH	OSC1↑ to CLKOUT↑ ^(1,2)	—	15	30**	ns
12	TckR	CLKOUT rise time ^(1,2)	—	5.0	15**	ns
13	TckF	CLKOUT fall time ^(1,2)	—	5.0	15**	ns
14	TckL2ioV	CLKOUT↓ to Port out valid ^(1,2)	—		40**	ns
15	TioV2ckH	Port in valid before CLKOUT ^(1,2)	0.25 TCY+30*	—	—	ns
16	TckH2iol	Port in hold after CLKOUT ^(1,2)	0*	—	—	ns
17	TosH2ioV	OSC1 [↑] (Q1 cycle) to Port out valid ⁽²⁾	—	—	100	ns
18	TosH2iol	OSC1↑ (Q2 cycle) to Port input invalid (I/O in hold time)	TBD	—	—	ns
19	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)	TBD	—	—	ns
20	TioR	Port output rise time ⁽²⁾	—	10	25**	ns
21	TioF	Port output fall time ⁽²⁾		10	25**	ns

* These parameters are characterized but not tested.

- ** These parameters are design targets and are not tested. No characterization data available at this time.
- † Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x Tosc.

2: Refer to Figure 19-2 for load conditions.

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FIGURE 19-6: TIMER0 CLOCK TIMINGS - PIC16C5X-40

TABLE 19-4: TIMER0 CLOCK REQUIREMENTS PIC16C5X-40

AC CharacteristicsStandard Operating Conditions (unless otherwise specified) Operating Temperature $0^{\circ}C \le TA \le +70^{\circ}C$ for commercial							
Param No.	Symbol	Characteristic	Min	Тур†	Max	Units	Conditions
40	Tt0H	T0CKI High Pulse Width					
		- No Prescaler	0.5 Tcy + 20*	—	—	ns	
		- With Prescaler	10*	_	_	ns	
41	Tt0L	T0CKI Low Pulse Width					
		- No Prescaler	0.5 Tcy + 20*	—	—	ns	
		- With Prescaler	10*	_	_	ns	
42	Tt0P	T0CKI Period	20 or <u>Tcy + 40</u> * N		_	ns	Whichever is greater. N = Prescale Value (1, 2, 4,, 256)

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 20-4: VTH (INPUT THRESHOLD TRIP POINT VOLTAGE) OF I/O PINS vs. VDD

FIGURE 20-5: VTH (INPUT THRESHOLD TRIP POINT VOLTAGE) OF OSC1 INPUT (HS MODE) vs. VDD

APPENDIX A: COMPATIBILITY

To convert code written for PIC16CXX to PIC16C5X, the user should take the following steps:

- 1. Check any CALL, GOTO or instructions that modify the PC to determine if any program memory page select operations (PA2, PA1, PA0 bits) need to be made.
- 2. Revisit any computed jump operations (write to PC or add to PC, etc.) to make sure page bits are set properly under the new scheme.
- 3. Eliminate any special function register page switching. Redefine data variables to reallocate them.
- 4. Verify all writes to STATUS, OPTION, and FSR registers since these have changed.
- 5. Change RESET vector to proper value for processor used.
- 6. Remove any use of the ADDLW, RETURN and SUBLW instructions.
- 7. Rewrite any code segments that use interrupts.

APPENDIX B: REVISION HISTORY

Revision KE (January 2013)

Added a note to each package outline drawing.